



Initial Product/Process Change Notification

Document #: IPCN23233X

Issue Date: 22 Apr 2020

Title of Change:	Change from Module Level Burn-in to Wafer Level Burn-in for CM8012 SiC Mosfet	
Proposed First Ship date:	22 Aug 2020 or earlier if approved by customer	
Contact Information:	Contact your local ON Semiconductor Sales Office or Way-Shan.Yong@onsemi.com	
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>	
Marking of Parts/ Traceability of Change:	No change	
Change Category:	Test Change, Assembly Change	
Change Sub-Category(s):	Manufacturing Process Change	
Sites Affected:		
ON Semiconductor Sites	External Foundry/Subcon Sites	
ON Semiconductor Shenzhen, China	None	
Description and Purpose:		
<p>This IPCN announces the change from Module Level Burn-in to Wafer Level Burn-in for CM8012 SiC Mosfet for PIM module. The change is planned at ON Semiconductor Shenzhen.</p> <p>Upon the expiration of this PCN, CM8012 SiC Mosfet for PIM module at ON Semiconductor Shenzhen will be run with Wafer Level Burn-in. Products has been qualified to industrial requirements and meeting customer product requirements.</p>		
	Before Change Description	After Change Description
Other Changes	Module Burn-In Biasing condition 170C, VGS 28V, 5hrs	Wafer level burn-in for CM8012 SiC Mosfet
<p>There are no product material changes as a result of this change.</p> <p>There is no product marking change as a result of this change</p>		
Qualification Plan:		
No reliability test is required for this change		

**List of Affected Parts:**

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
NXH40B120MNQ0SNG	NXH40B120MNQ0SNG
NXH80B120MNQ0SNG	NXH40B120MNQ0SNG
NXH40B120MNQ1SNG	NXH40B120MNQ0SNG